Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

NTMFS4826NE

Power MOSFET
30 V, 66 A, Single N−Channel, SO−8FL

Features
- Low $R_{DS(on)}$ to Minimize Conduction Losses
- Low Capacitance to Minimize Driver Losses
- Optimized Gate Charge to Minimize Switching Losses
- Dual Sided Cooling Capability
- These are Pb−Free Devices*

Applications
- CPU Power Delivery
- DC−DC Converters
- High Side Switching

MAXIMUM RATINGS (T_J = 25°C unless otherwise stated)

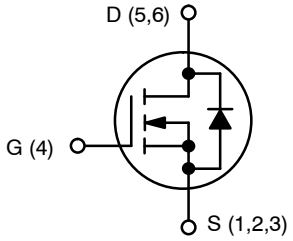
Parameter			Symbol	Value	Unit
Drain−to−Source Voltage			V_{DSS}	30	V
Gate−to−Source Voltage			V_{GS}	±20	V
Continuous Drain Current $R_{\theta JA}$ (Note 1)	Steady State	T_A = 25°C	I_D	15	A
		T_A = 85°C		10.8	
Power Dissipation $R_{\theta JA}$ (Note 1)		T_A = 25°C	P_D	2.16	W
Continuous Drain Current $R_{\theta JA}$ ≤ 10 sec		T_A = 25°C	I_D	24.3	A
		T_A = 85°C		17.5	
Power Dissipation $R_{\theta JA}$, t ≤ 10 sec		T_A = 25°C	P_D	5.67	W
Continuous Drain Current $R_{\theta JA}$ (Note 2)		T_A = 25°C	I_D	9.5	A
		T_A = 85°C		6.9	
Power Dissipation $R_{\theta JA}$ (Note 2)		T_A = 25°C	P_D	0.87	W
Continuous Drain Current $R_{\theta JC}$ (Note 1)		T_C = 25°C	I_D	66	A
		T_C = 85°C		47.8	
Power Dissipation $R_{\theta JC}$ (Note 1)		T_C = 25°C	P_D	41.7	W
Pulsed Drain Current	t_p=10μs	T_A = 25°C	I_{DM}	132	A
Current limited by package		T_A = 25°C	$I_{Dmaxpkg}$	100	A
Operating Junction and Storage Temperature			T_J, T_{STG}	−40 to +150	°C
Source Current (Body Diode)			I_S	41.7	A
Drain to Source dV/dt			dV/dt	6	V/ns
Single Pulse Drain−to−Source Avalanche Energy (V_{DD} = 50 V, V_{GS} = 10 V, I_L = 27 A_{pk}, L = 0.3 mH, R_G = 25 Ω)			EAS	109	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			T_L	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

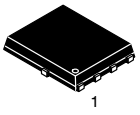
ON Semiconductor®

http://onsemi.com

$V_{(BR)DSS}$	$R_{DS(ON)}$ MAX	I_D MAX
30 V	5.9 mΩ @ 10 V	66 A
	8.7 mΩ @ 4.5 V	55 A

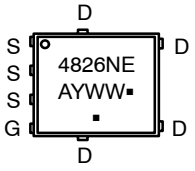


N−CHANNEL MOSFET



SO−8 FLAT LEAD CASE 488AA STYLE 1

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
▪ = Pb−Free Package
(Note: Microdot may be in either location)

ORDERING INFORMATION

Device	Package	Shipping†
NTMFS4826NET1G	SO−8FL (Pb−Free)	1500 / Tape & Reel
NTMFS4826NET3G	SO−8FL (Pb−Free)	5000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction−to−Case (Drain)	$R_{\theta JC}$	3.0	°C/W
Junction−to−Ambient − Steady State (Note 1)	$R_{\theta JA}$	57.8	
Junction−to−Ambient − Steady State (Note 2)	$R_{\theta JA}$	143.5	
Junction−to−Ambient − t ≤ 10 sec	$R_{\theta JA}$	22.1	
Junction−to−Top	$R_{\theta JT}$	9.7	

1. Surface−mounted on FR4 board using 1 sq−in pad, 1 oz Cu.
2. Surface−mounted on FR4 board using the minimum recommended pad size.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
OFF CHARACTERISTICS							
Drain−to−Source Breakdown Voltage	$V_{(BR)DSS}$	V_{GS} = 0 V, I_D = 250 μA		30			V
Drain−to−Source Breakdown Voltage Temperature Coefficient	$V_{(BR)DSS}/T_J$				25		mV/°C
Zero Gate Voltage Drain Current	I_{DSS}	V_{GS} = 0 V, V_{DS} = 24 V	T_J = 25 °C			1	μA
			T_J = 125°C			10	
Gate−to−Source Leakage Current	I_{GSS}	V_{DS} = 0 V, V_{GS} = ±16 V				±100	nA
ON CHARACTERISTICS (Note 3)							
Gate Threshold Voltage	$V_{GS(TH)}$	V_{GS} = V_{DS}, I_D = 250 μA		1.45	1.8	2.5	V
Negative Threshold Temperature Coefficient	$V_{GS(TH)}/T_J$				4.6		mV/°C
Drain−to−Source On Resistance	$R_{DS(on)}$	V_{GS} = 10 V to 11.5 V	I_D = 30 A		4.3	5.9	mΩ
			I_D = 15 A		4.2		
		V_{GS} = 4.5 V	I_D = 30 A		6.6	8.7	
			I_D = 15 A		6.5		
Forward Transconductance	g_{FS}	V_{DS} = 1.5 V, I_D = 30 A			62		S
CHARGES AND CAPACITANCES							
Input Capacitance	C_{ISS}	V_{GS} = 0 V, f = 1 MHz, V_{DS} = 12 V			1850		pF
Output Capacitance	C_{OSS}				333		
Reverse Transfer Capacitance	C_{RSS}				170		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 4.5 V, V_{DS} = 15 V; I_D = 30 A			13.5	20	nC
Threshold Gate Charge	$Q_{G(TH)}$				1.7		
Gate−to−Source Charge	Q_{GS}				5.1		
Gate−to−Drain Charge	Q_{GD}				4.5		
Total Gate Charge	$Q_{G(TOT)}$	V_{GS} = 11.5 V, V_{DS} = 15 V, I_D = 30 A			32		nC
SWITCHING CHARACTERISTICS (Note 4)							
Turn−On Delay Time	$t_{d(ON)}$	V_{GS} = 4.5 V, V_{DS} = 15 V, I_D = 15 A, R_G = 3.0 Ω			14.4		ns
Rise Time	t_r				39.8		
Turn−Off Delay Time	$t_{d(OFF)}$				18.6		
Fall Time	t_f				5.2		

3. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
4. Switching characteristics are independent of operating junction temperatures.

ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Typ	Max	Unit
SWITCHING CHARACTERISTICS (Note 4)							
Turn−On Delay Time	$t_{d(ON)}$	V_{GS} = 11.5 V, V_{DS} = 15 V, I_D = 15 A, R_G = 3.0 Ω			9.5		ns
Rise Time	t_r				22		
Turn−Off Delay Time	$t_{d(OFF)}$				25		
Fall Time	t_f				4.6		
DRAIN−SOURCE DIODE CHARACTERISTICS							
Forward Diode Voltage	V_{SD}	V_{GS} = 0 V, I_S = 30 A	T_J = 25°C		0.84	1.0	V
			T_J = 125°C		0.73		
Reverse Recovery Time	t_{RR}	V_{GS} = 0 V, dI_S/dt = 100 A/μs, I_S = 30 A			13.2		ns
Charge Time	t_a				8.5		
Discharge Time	t_b				4.7		
Reverse Recovery Charge	Q_{RR}				3.5		nC
PACKAGE PARASITIC VALUES							
Source Inductance	L_S	T_A = 25°C			0.93		nH
Drain Inductance	L_D				0.005		
Gate Inductance	L_G				1.84		
Gate Resistance	R_G				0.9		Ω

3. Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
4. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

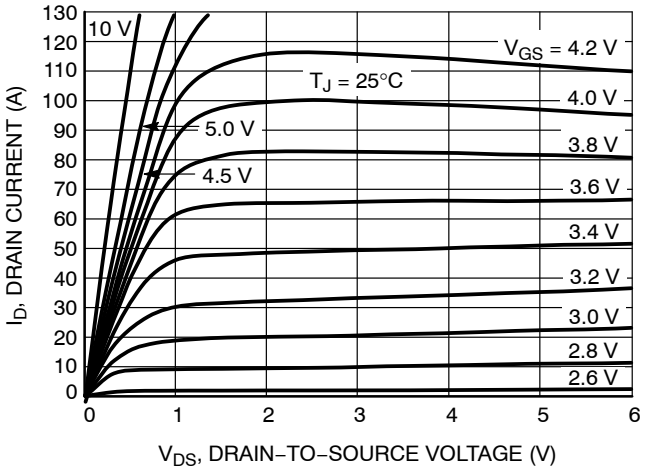


Figure 1. On−Region Characteristics

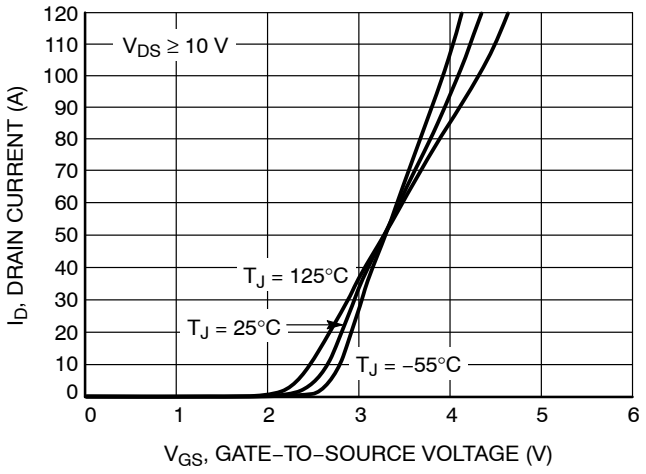


Figure 2. Transfer Characteristics

TYPICAL CHARACTERISTICS

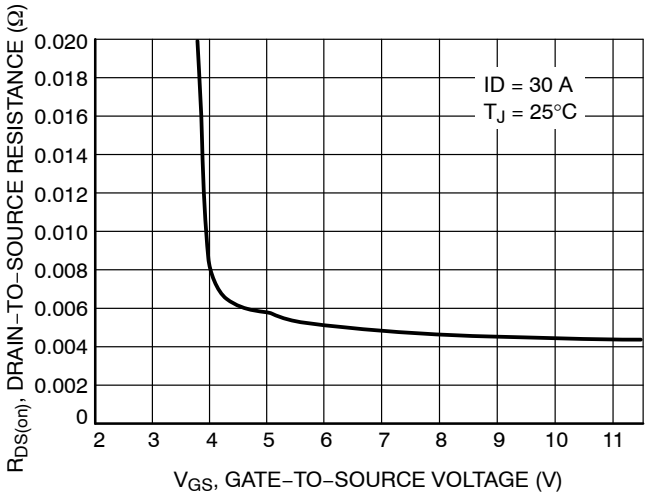


Figure 3. On−Resistance vs. Gate−to−Source Voltage

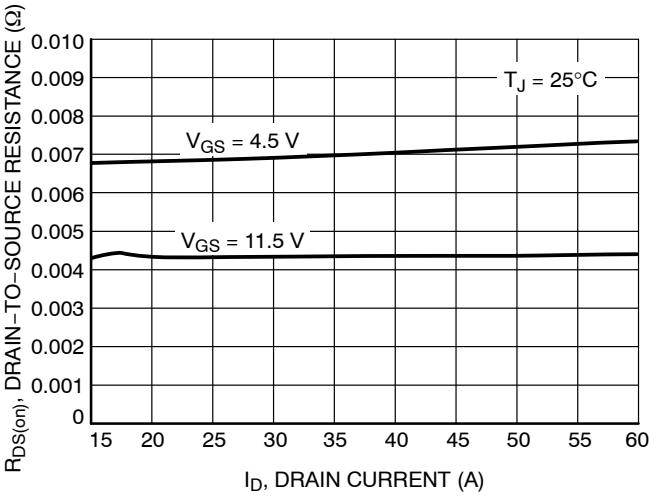


Figure 4. On−Resistance vs. Drain Current and Gate Voltage

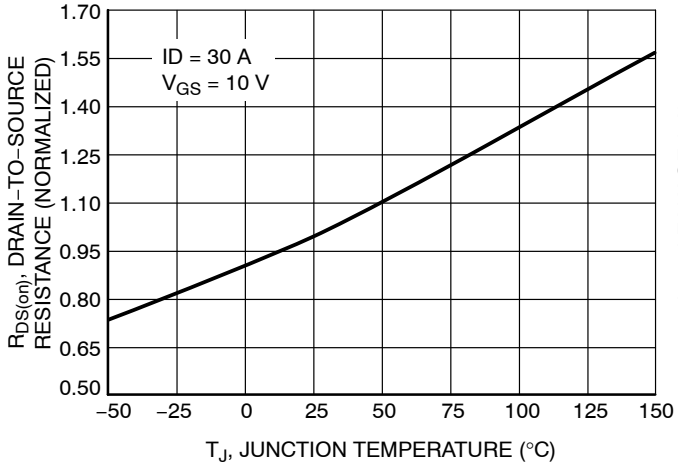


Figure 5. On−Resistance Variation with Temperature

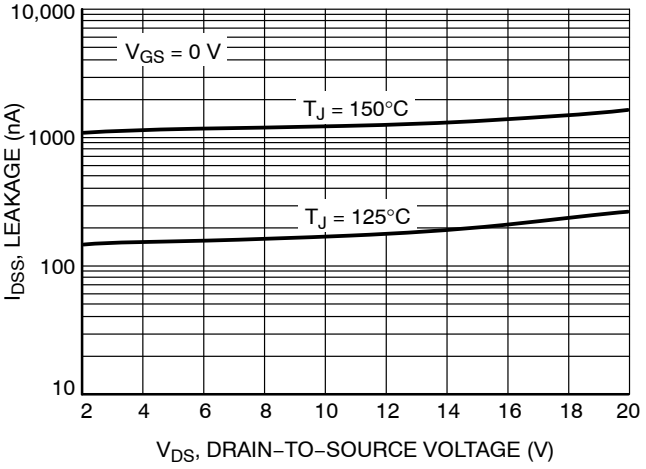


Figure 6. Drain−to−Source Leakage Current vs. Voltage

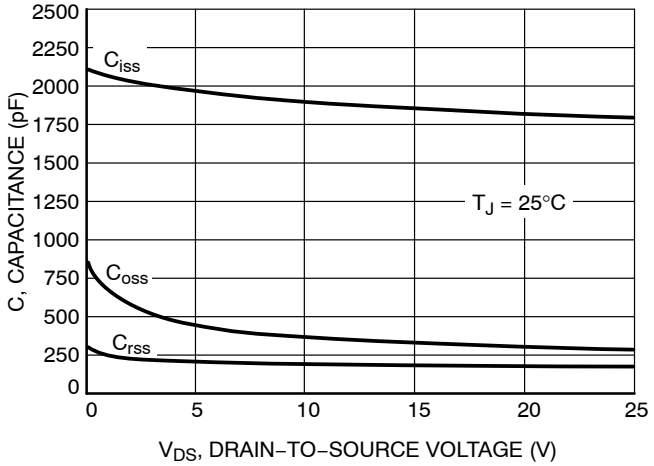


Figure 7. Capacitance Variation

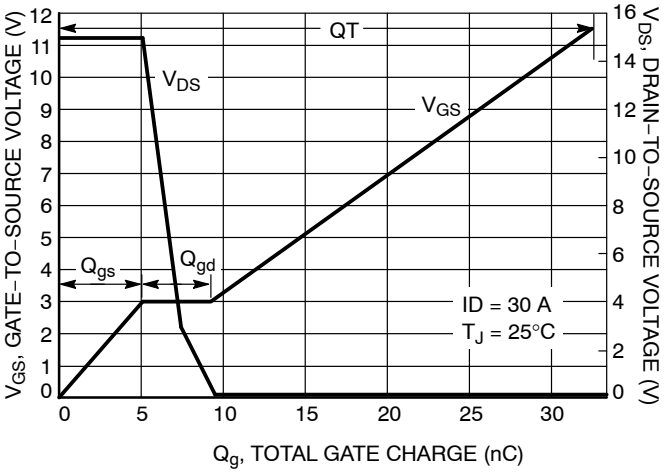


Figure 8. Gate−to−Source and Drain−to−Source Voltage vs. Total Charge

TYPICAL CHARACTERISTICS

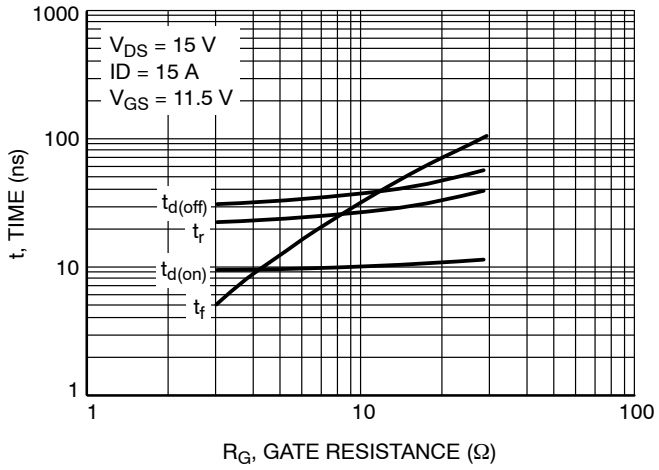


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

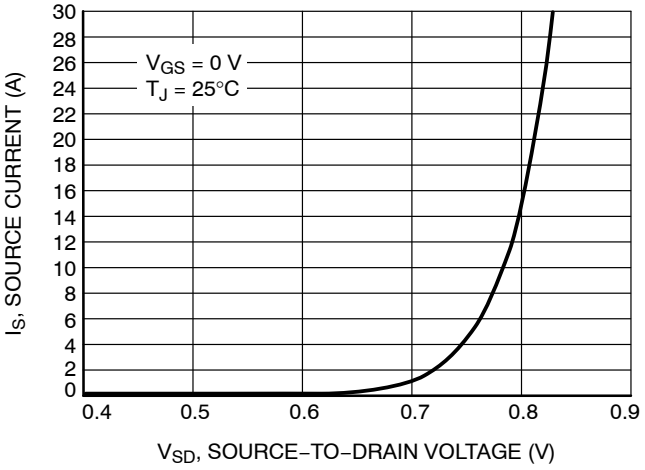


Figure 10. Diode Forward Voltage vs. Current

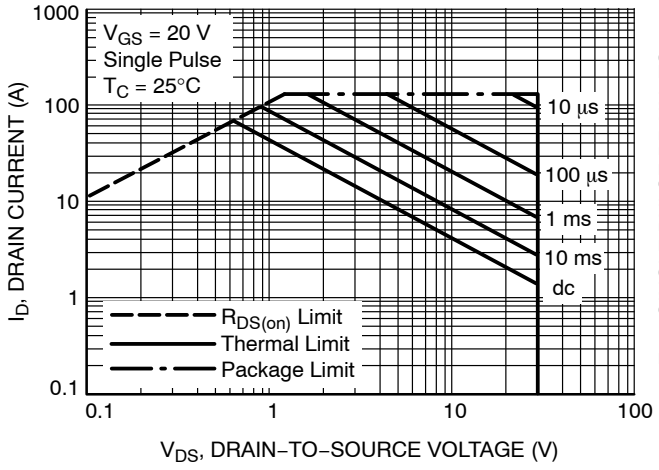


Figure 11. Maximum Rated Forward Biased Safe Operating Area

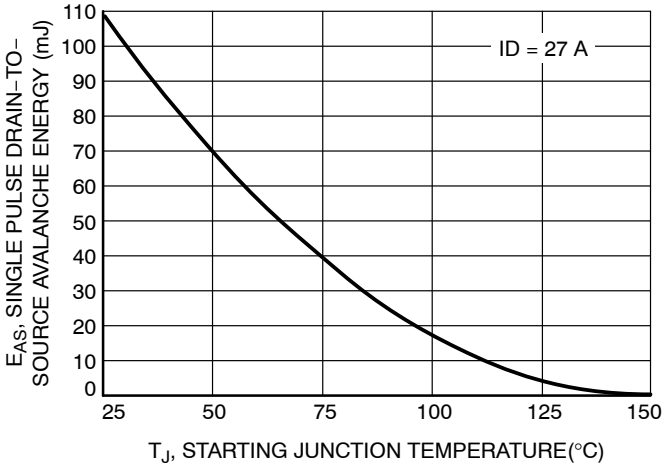


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

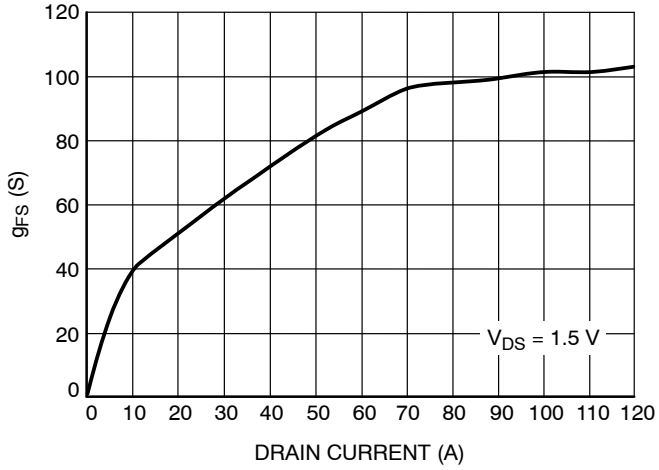


Figure 13. g_{FS} vs. Drain Current

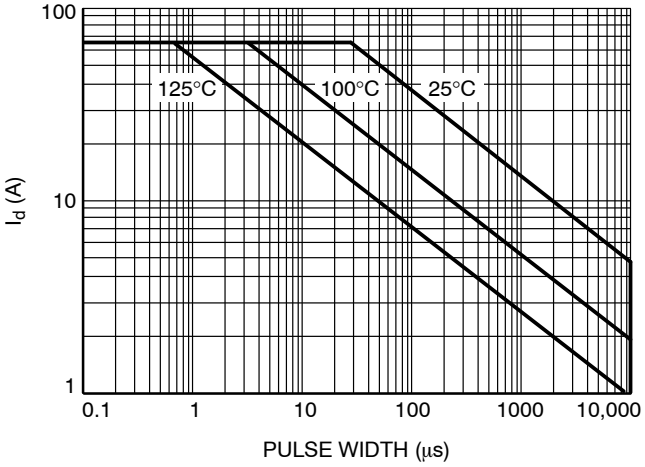
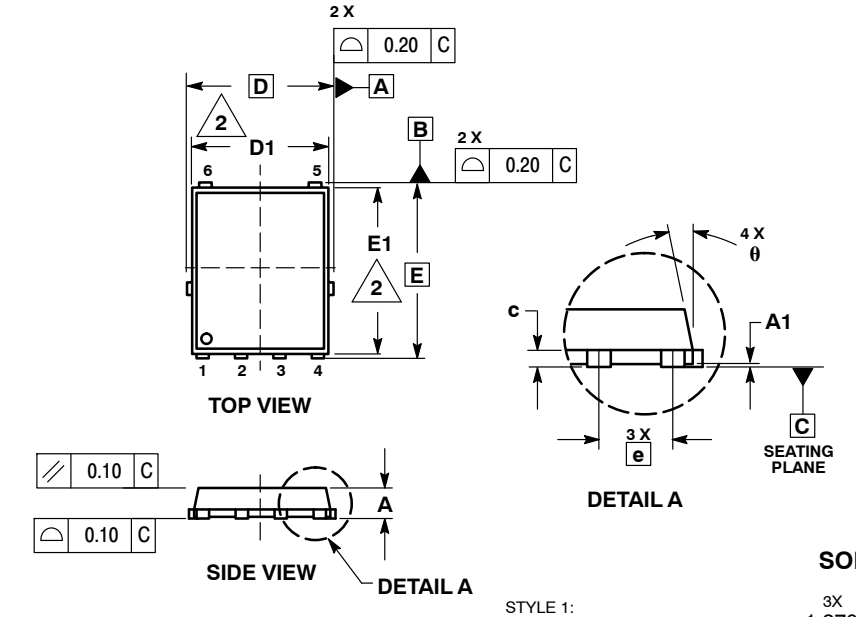


Figure 14. Avalanche Characteristics

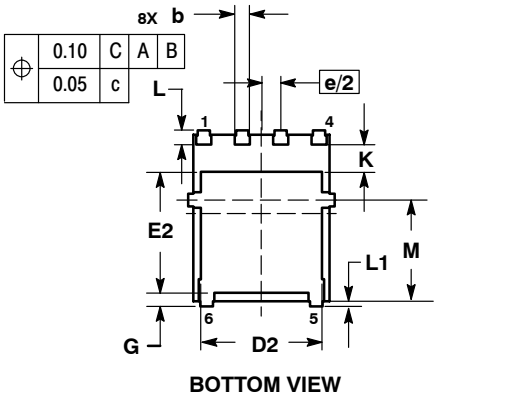
PACKAGE DIMENSIONS

DFN5 5x6, 1.27P
(SO−8FL)
CASE 488AA−01
ISSUE D



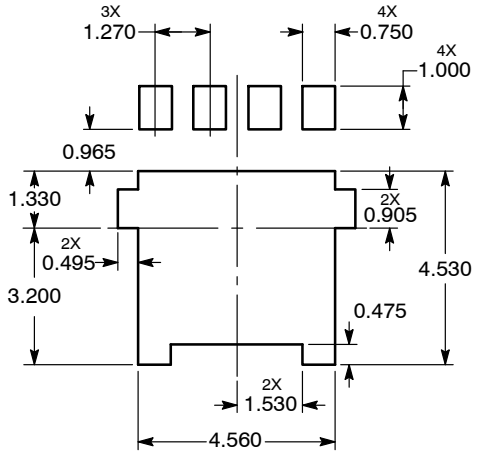
NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	0.90	1.00	1.10
A1	0.00	−−−	0.05
b	0.33	0.41	0.51
c	0.23	0.28	0.33
D		5.15 BSC	
D1	4.50	4.90	5.10
D2	3.50	−−−	4.22
E		6.15 BSC	
E1	5.50	5.80	6.10
E2	3.45	−−−	4.30
e		1.27 BSC	
G	0.51	0.61	0.71
K	0.51	−−−	−−−
L	0.51	0.61	0.71
L1	0.05	0.17	0.20
M	3.00	3.40	3.80
θ	0 °	−−−	12 °



STYLE 1:
PIN 1. SOURCE
2. SOURCE
3. SOURCE
4. GATE
5. DRAIN
6. DRAIN

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
P.O. Box 5163, Denver, Colorado 80217 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5773−3850

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative

NTMFS4826NE/D